IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2020) will be held in Suzhou, China on July 29-31, 2020. IMWS-AMP 2020 will feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches on technology trends and significant advances in relevant topics. Contributed papers are solicited for the same topics as listed below.

Topics

The topics include, but are not limited to, the following technical areas:

- Carbon nanotubes and 2D electronic and optoelectronic devices (e.g. graphene and beyond graphene)
- Wide bandgap and other emerging semiconductor materials (e.g. ionic materials) based electronic devices: characterization, modeling and design
- Advanced silicon, integrated passive devices and through substrate via
- Low-temperature co-fired ceramic and liquid crystal polymer based microwave devices
- Large-area printing, inkjet printing and 3D printing materials and processes for RF and THz applications
- Engineered metamaterials and plasmonics for absorption, cloaking, and wave manipulation
- Ferromagnetic materials and superconducting materials
- Spin-wave and magnetic crystal materials
- Passive/active microwave and terahertz devices (material characterization, fabrications, and applications)
- Antennas with advanced/complex/artificial materials and processes

Electronic Paper Submission:

Prospective authors are invited to submit manuscripts in electronic (PDF) format only. All papers must be written in English and limited to three pages including text, references, and figures. A template is available on the IMWS-AMP 2020 website. Papers submitted will be peer reviewed and all papers presented at the conference will be included in IEEE Xplore pending quality review.

Important Dates:

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<td>Paper Submission Deadline</td>
<td>February 23, 2020</td>
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<tr>
<td>Notification of Acceptance</td>
<td>April 27, 2020</td>
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<td>Final paper Submission</td>
<td>May 18, 2020</td>
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Exhibitions:

Exhibition of company products is solicited for the areas related to the topics. Interested parties should contact the Conference Secretariat.